CLAIMS

1. A lithography system comprising:

a printing tool with an integrated metrology tool, and

a standalone metrology tool connected to the printing tool and configured to perform metrology measurements on wafers produced by the printing tool,

wherein the lithography system further comprises a monitoring channel connecting the integrated metrology tool with the standalone metrology tool, and the integrated metrology tool is further configured to allocate metrology measurements between the integrated metrology tool and the standalone metrology tool and monitor the allocation and the metrology measurement with respect to specified temporal limitations of the printing tool.

2. The lithography system of claim 1, wherein the monitoring comprises adjusting a metrology measurement recipe according to the specified temporal limitations.

3. The lithography system of claim 1, further comprising an optimization channel connecting the integrated metrology tool with a metrology tool configured to optimize a metrology measurement recipe for the lithography system.

4. The lithography system of claim 3, wherein the metrology tool is the standalone metrology tool.

5. The lithography system of claim 1, further comprising a process control channel connecting the integrated metrology tool with process control software configured to optimize process parameters of the printing tool.

6. The lithography system of claim 1, further comprising a grouping channel connecting the integrated metrology tool with a grouping module configured to group process parameters of the printing tool according to a metrology measurements landscape.

7. The lithography system of claim 6, wherein the metrology measurements landscape is an at least partially continuous dependency of at least one metrology metric on at least one recipe parameter, derived by the respective metrology tool.

8. The lithography system of claim **1**, further comprising a grouping channel connecting the standalone metrology tool with a grouping module configured to group process parameters of the printing tool according to a metrology measurements landscape.

9. The lithography system of claim **8**, wherein the metrology measurements landscape is an at least partially continuous dependency of at least one metrology metric on at least one recipe parameter, derived by the respective metrology tool.

10. A method comprising allocating and monitoring, by an integrated metrology tool of a lithography printing tool, metrology measurements by the integrated metrology tool and a standalone metrology tool with respect to specified temporal limitations of the printing tool, wherein the monitoring comprises adjusting a metrology measurement recipe according to the specified temporal limitations.

11. The method of claim **10**, further comprising optimizing process parameters of the printing tool by process control software, based on metrology measurements by at least the integrated metrology tool.

12. The method of claim **10**, further comprising grouping process parameters of the printing tool according to a metrology measurements landscape.

13. The method of claim **12**, further comprising deriving the metrology measurements landscape by at least the integrated metrology tool.

14. The method of claim **10**, carried out at least partly by a computer processor.

15. A computer program product comprising a non-transitory computer readable storage medium having a computer readable program embodied therewith, the computer readable program configured to carry out the method of claim **10**.

16. The method of claim **10**, wherein the adjusting comprises optimizing the metrology measurement recipe according to the specified temporal limitations.